

Title (en)

CIRCUIT BOARD MANUFACTURING METHOD AND CIRCUIT BOARD

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER LEITERPLATTE UND LEITERPLATTE

Title (fr)

PROCÉDÉ DE FABRICATION D'UNE CARTE DE CIRCUITS ET CARTE DE CIRCUITS

Publication

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Application

**EP 16908905 A 20161202**

Priority

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Abstract (en)

A method of producing a circuit board includes: a step of removing a temporary substrate from a circuit that is formed on the temporary substrate, and a step of disposing the circuit on an insulating layer, in such a manner that a side of the circuit that faced the temporary substrate faces the insulating layer.

IPC 8 full level

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CPC (source: EP)

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